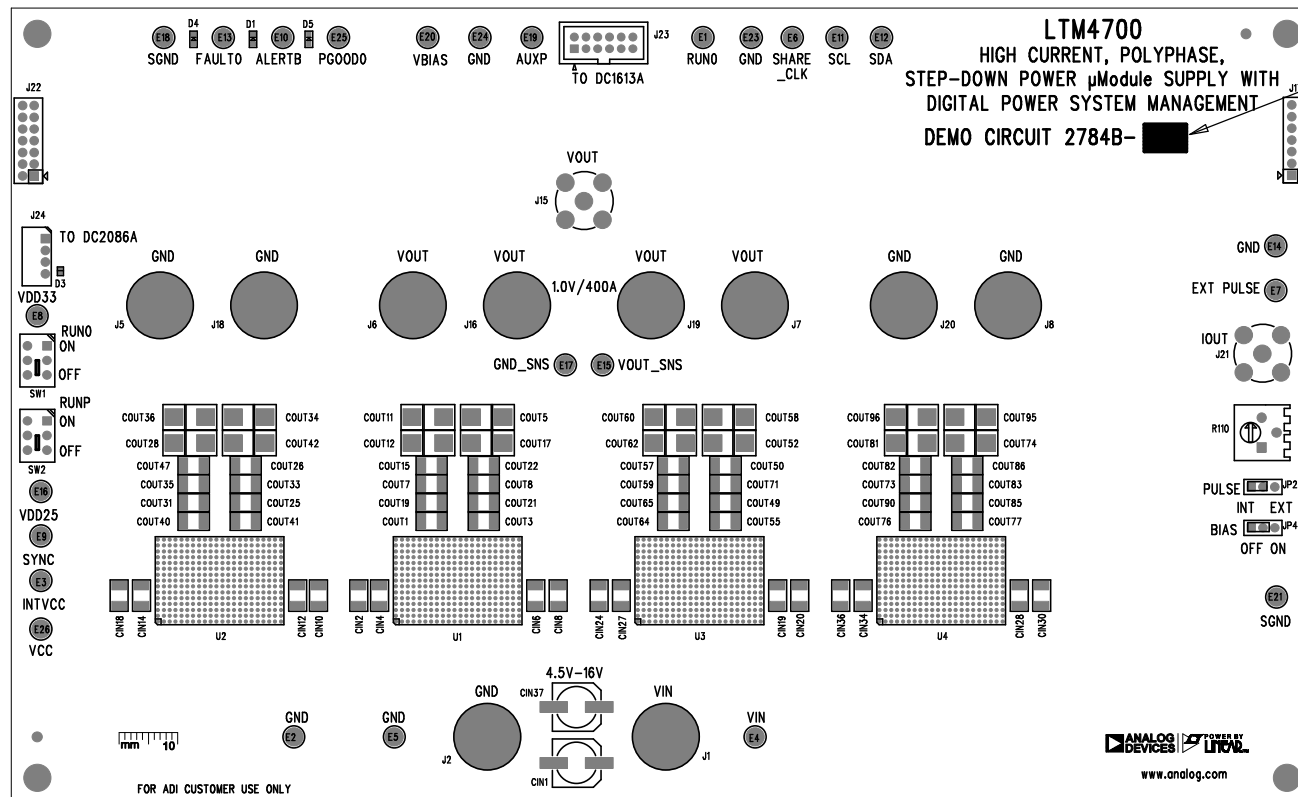


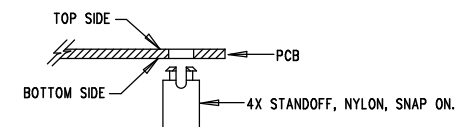
REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG. DATE
-	1	PRODUCTION	SG 07-26-21



LAYER 1 - TOP SIDE

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL STANDOFFS AS SHOWN BELOW:



8. SEE THE BILL OF MATERIALS TO MARK THE APPROPRIATE ASSEMBLY TYPE WITH BLACK PERMANENT MARKER.

APPROVALS		ANALOG DEVICES POWER BY LINEAR	
PCB DES.	LT	www.analog.com FOR ADI CUSTOMER USE ONLY	
APP ENG.	SG	TITLE: TOP ASSEMBLY DRAWING HIGH CURRENT, POLYPHASE, STEP-DOWN POWER μModule SUPPLY WITH DIGITAL POWER SYSTEM MANAGEMENT	
		SIZE	REV.
		N/A	1
SCALE = NONE		FILENAME: DC2784B-1.PCB	SHT 1 OF 2